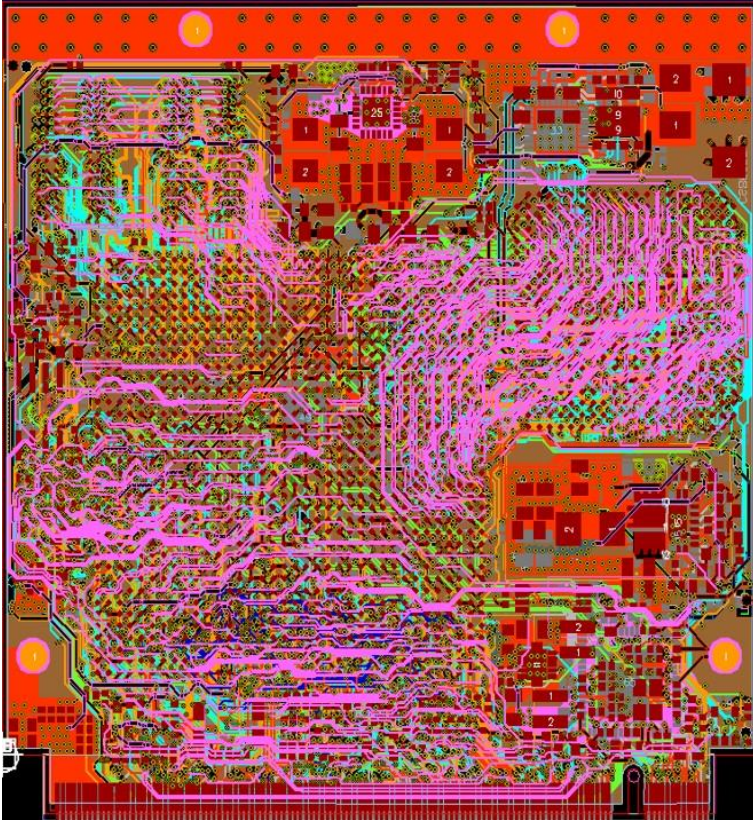
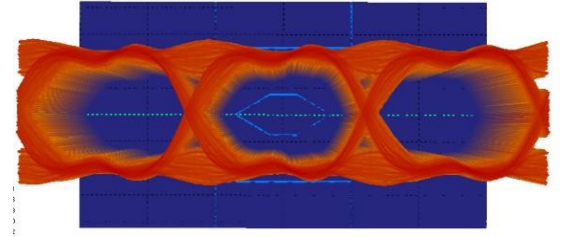


# PCB DESIGN AND ANALYSIS

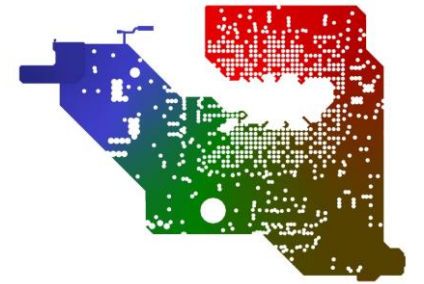


## TECHNOLOGIES:

- Digital high speed (DDR4, SERDES, USB3, etc)
- Power BOARD (OVER 100Amp\_base copper 6oz), switching module)
- Mixed Technologies, ANALOG BOARD



Signal integrity



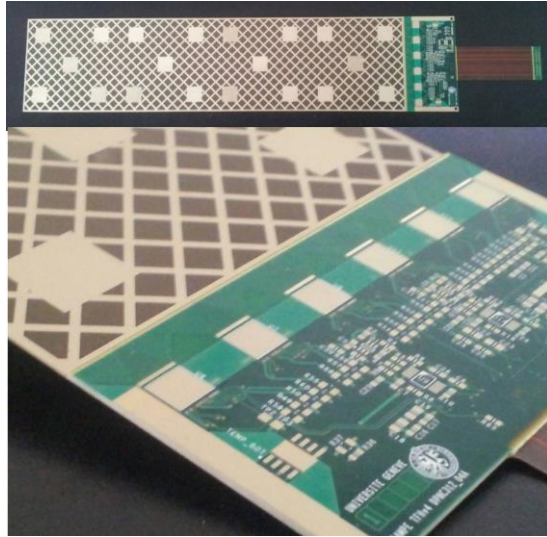
Power analysis



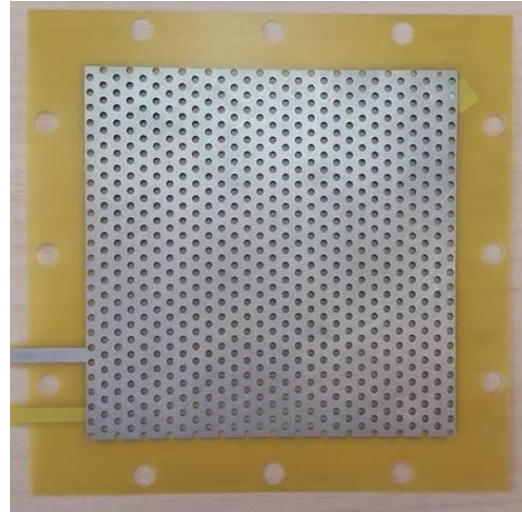
Thermal analysis

PCB design, production and assembly in according to standard IPC

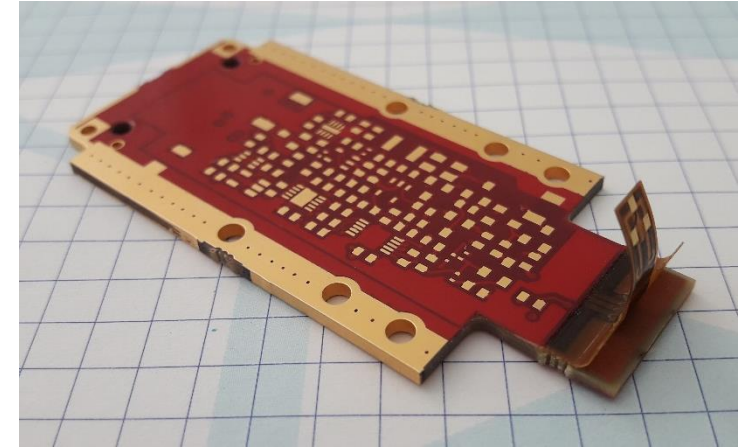
# PCB PRODUCTION



*16 layer mixed material ENEPIG*



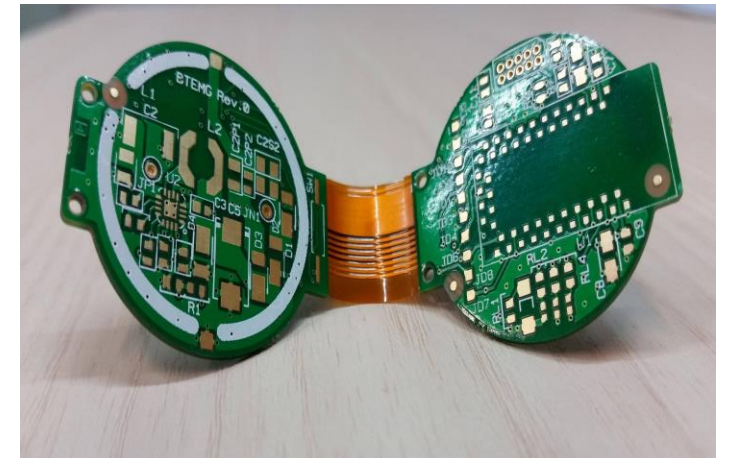
*Aluminium trace over FR4*



*Rigid-flex polyimide base material*



COPPER HEATSINK

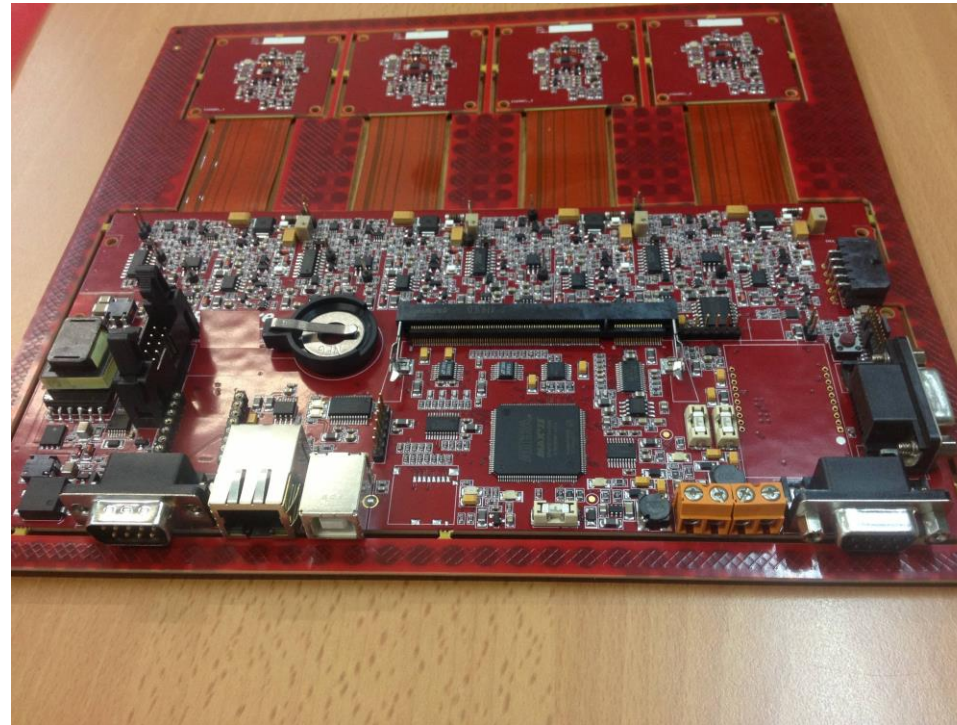




# PRODUCTION & ASSEMBLY

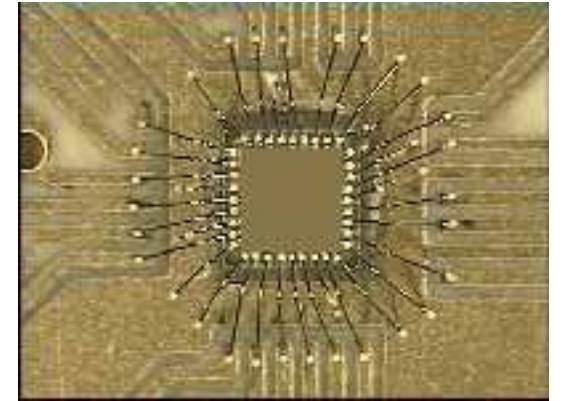


Module *assembly*



PCB assembly

Bonding



PCB assembly

